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 Title: **JP61240629A2: MANUFACTURE OF SUBSTRATE**

 Derwent Title: Substrate for semiconductor mfr. - forming diamond thin layer or 1st substrate, junction layer on it bonding 2nd eliminating 1st substrate
NoAbstract Dwg 0/1 [\[Derwent Record\]](#)

 Country: **JP Japan**

 Kind: **A (See also: JP6065210B4)**


 Inventor: **SHOHATA NOBUAKI;**
FUJII KAZUTAKA;


 Assignee: **NEC CORP**
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 Published / Filed: **1986-10-25 / 1985-04-17**

 Application Number: **JP1985000081559**

 IPC Code: **H01L 21/205; H01L 21/304;**


 Priority Number: **1985-04-17 JP1985000081559**

 Abstract: **PURPOSE:** To obtain a substrate equipped with a diamond shape thin film having superior surface flatness, by jointing the second substrate, through a jointed layer, on the diamond shape thin film formed on the first substrate and then removing the first substrate.

CONSTITUTION: A silicon substrate 2 of 0.3mm in thickness is used as the first substrate 1 and a diamond-shape thin film 2 is deposited on it by exciting a mixing gas of CH₄ and H₂ with high frequency non-polar discharge with frequency of 13.56MHz. A jointed layer 3 is a material evaporation deposited and metallized with Ti, Pt, and Au. A silicon substrate of 0.3mm in thickness, which has been similarly metallized, is used as the second substrate 4 and jointed with an Au layer being fuse-bonded. The first substrate can be removed by grinding, however, the possibly remaining part of silicon, which can not be removed by grinding, is removed by well-known method.

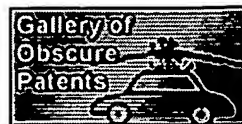
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 Other Abstract Info: **DERABS C87-009700 DERC87-009700**





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